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SERIAL NUMBER 10/671,712	FILING DATE 09/29/2003  RULE	CLASS 419	GROUP ART UNIT 1742	ATTORNEY DOCKET NO. Q77443
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**\*\* CONTINUING DATA \*\*\*\*\***

This application is a DIV of 09/252,880 02/18/1999 PAT 6,693,353

yes

**\*\* FOREIGN APPLICATIONS \*\*\*\*\***

JAPAN 325445/1998 11/16/1998

JAPAN 1772/1999 01/07/1999

yes

**IF REQUIRED, FOREIGN FILING LICENSE GRANTED****\*\* 12/18/2003**

Foreign Priority claimed 35 USC 119 (a-d) conditions met Verified and Acknowledged	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance Examiner's Signature _____ Initials _____	STATE OR  COUNTRY JAPAN	SHEETS  DRAWING 5	TOTAL  CLAIMS 7	INDEPENDENT  CLAIMS 3
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**ADDRESS**

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**TITLE**

Semiconductor package and method for producing heat-radiating substrate for it

FILING FEE	FEES: Authority has been given in Paper	<input type="checkbox"/> All Fees
		<input type="checkbox"/> 1.16 Fees ( Filing )
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